



QUAD DIGITAL ISOLATORS

FEATURES

- 1, 25, and 150-Mbps Signaling Rate Options
 - Low Channel-to-Channel Output Skew;
1 ns Max
 - Low Pulse-Width Distortion (PWD);
2 ns Max
 - Low Jitter Content; 1 ns Typ at 150 Mbps
- Typical 25-Year Life at Rated Working Voltage (see application note [SLLA197](#) and [Figure 15](#))
- 4000-V_{peak} Isolation, 560-V_{peak} Working Voltage
- UL 1577 Certified
- 4 kV ESD Protection
- Operate With 3.3-V or 5-V Supplies

- High Electromagnetic Immunity (see application report [SLLA181](#))
- –40°C to 125°C Operating Range

APPLICATIONS

- Industrial Fieldbus
- Computer Peripheral Interface
- Servo Control Interface
- Data Acquisition

DESCRIPTION

The ISO7240, ISO7241 and ISO7242 are quad-channel digital isolators with multiple channel configurations and output enable functions. These devices have logic input and output buffers separated by TI's silicon dioxide (SiO₂) isolation barrier. Used in conjunction with isolated power supplies, these devices block high voltage, isolate grounds, and prevent noise currents from entering the local ground and interfering with or damaging sensitive circuitry.

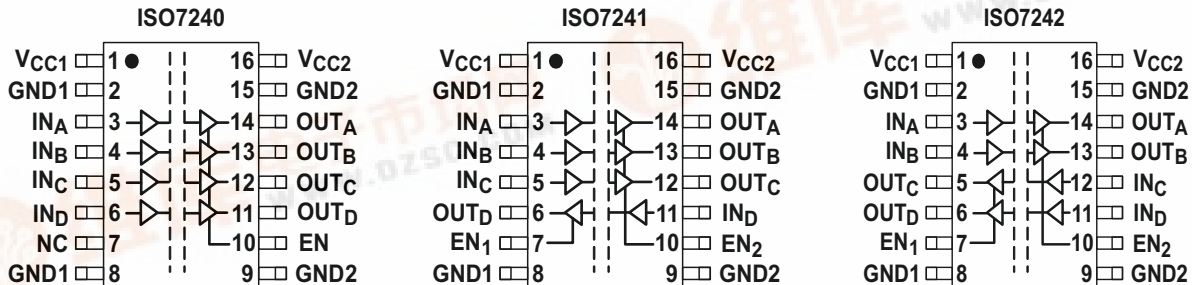
The ISO7240 has all four channels in the same direction while the ISO7241 has three channels the same direction and one channel in opposition. The ISO7242 has two channels in each direction.

The A and C option devices have TTL input thresholds and a noise-filter at the input that prevents transient pulses from being passed to the output of the device. The M option devices have CMOS V_{cc}/2 input thresholds and do not have the input noise-filter or the additional propagation delay.

A periodic update pulse is sent across the barrier to ensure the proper dc level of the output. If this dc-refresh pulse is not received, the input is assumed to be unpowered or not being actively driven, and the failsafe circuit drives the output to a logic high state. (Contact TI for a logic low failsafe option).

These devices may be powered from either 3.3-V or 5-V supplies on either side in any 3.3-V / 3.3-V, 5-V / 5-V, 5-V / 3.3-V, or 3.3-V / 5-V combination. Note that the signal input pins are 5-V tolerant regardless of the voltage supply level being used.

These devices are characterized for operation over the ambient temperature range of –40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

FUNCTION DIAGRAM

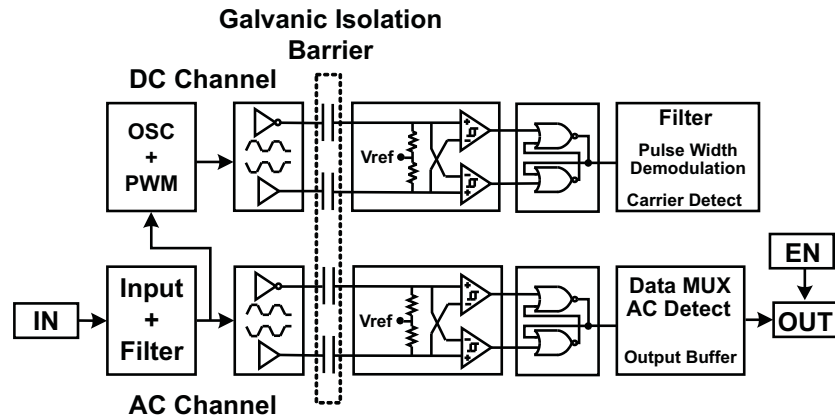


Table 1. Device Function Table ISO724x ⁽¹⁾

V_{CC1}	V_{CC2}	INPUT (IN)	OUTPUT ENABLE (EN)	OUTPUT (OUT)
PU	PU	H	H or Open	H
		L	H or Open	L
		X	L	Z
		Open	H or Open	H
PD	PU	X	H or Open	H
PD	PU	X	L	Z

(1) PU = Powered Up; PD = Powered Down ; X = Irrelevant; H = High Level; L = Low Level

AVAILABLE OPTIONS

PRODUCT	SIGNALING RATE	INPUT THRESHOLD	CHANNEL CONFIGURATION	MARKED AS	ORDERING NUMBER ⁽¹⁾
ISO7240ADW	1 Mbps	~1.5 V (TTL) (CMOS compatible)	4/0	ISO7240A	ISO7240ADW (rail)
					ISO7240ADWR (reel)
ISO7240CDW	25 Mbps	~1.5 V (TTL) (CMOS compatible)		ISO7240C	ISO7240CDW (rail)
					ISO7240CDWR (reel)
ISO7240MDW	150 Mbps	V _{cc} /2 (CMOS)		ISO7240M	ISO7240MDW (rail)
					ISO7240MDWR (reel)
ISO7241ADW	1 Mbps	~1.5 V (TTL) (CMOS compatible)	3/1	ISO7241A	ISO7241ADW (rail)
					ISO7241ADWR (reel)
ISO7241CDW	25 Mbps	~1.5 V (TTL) (CMOS compatible)		ISO7241C	ISO7241CDW (rail)
					ISO7241CDWR (reel)
ISO7241MDW	150 Mbps	V _{cc} /2 (CMOS)		ISO7241M	ISO7241MDW (rail)
					ISO7241MDWR (reel)
ISO7242ADW	1 Mbps	~1.5 V (TTL) (CMOS compatible)	2/2	ISO7242A	ISO7242ADW (rail)
					ISO7242ADWR (reel)
ISO7242CDW	25 Mbps	~1.5 V (TTL) (CMOS compatible)		ISO7242C	ISO7242CDW (rail)
					ISO7242CDWR (reel)
ISO7242MDW	150 Mbps	V _{cc} /2 (CMOS)		ISO7242M	ISO7242MDW (rail)
					ISO7242MDWR (reel)

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

				VALUE	UNIT	
V_{CC}	Supply voltage ⁽²⁾ , V_{CC1} , V_{CC2}			-0.5 to 6	V	
V_I	Voltage at IN, OUT, EN			-0.5 to 6	V	
I_O	Output current			±15	mA	
ESD	Electrostatic discharge	Human Body Model	JEDEC Standard 22, Test Method A114-C.01	All pins	±4	kV
		Field-Induced-Charged Device Model	JEDEC Standard 22, Test Method C101		±1	
		Machine Model	ANSI/ESDS5.2-1996		±200	V
T_J	Maximum junction temperature			170	°C	

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal and are peak voltage values.

RECOMMENDED OPERATING CONDITIONS

				MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage, V_{CC1} , V_{CC2}			4.5		5.5	V
				3.15		3.45	
I_{OH}	High-level output current					4	mA
I_{OL}	Low-level output current			-4			mA
t_{ui}	Input pulse width	ISO724xA		1			µs
		ISO724xC		40			ns
		ISO724xM		6.67	5		
$1/t_{ui}$	Signaling rate	ISO724xA		0	1500 ⁽¹⁾	1000	kbps
		ISO724xC		0	30 ⁽¹⁾	25	Mbps
		ISO724xM		0	200 ⁽¹⁾	150	
V_{IH}	High-level input voltage (IN)	ISO724xM		0.7 V_{CC}		V_{CC}	V
V_{IL}	Low-level input voltage (IN)			0	0.3 V_{CC}		V
V_{IH}	High-level input voltage (IN) (EN on all devices)	ISO724xA, ISO724xC		2		V_{CC}	V
V_{IL}	Low-level input voltage (IN) (EN on all devices)			0		0.8	V
T_J	Junction temperature					150	°C
H	External magnetic field-strength immunity per IEC 61000-4-8 and IEC 61000-4-9 certification					1000	A/m

- (1) Typical value at room temperature and well-regulated power supply.

ELECTRICAL CHARACTERISTICS

V_{CC1} and V_{CC2} at 5-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY CURRENT							
I_{CC1}	ISO7240A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	1	3		mA
	ISO7240A	1 Mbps		1	3		
	ISO7240C/M	25 Mbps		7	10.5		
	ISO7241A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	6.5	10		mA
	ISO7241A	1 Mbps		6.5	10		
	ISO7241C/M	25 Mbps		12	18		
	ISO7242A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	10	16		mA
	ISO7242A	1 Mbps		10	16		
ISO7242C/M	25 Mbps	15		24			
I_{CC2}	ISO7240A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	15	22		mA
	ISO7240A	1 Mbps		16	22		
	ISO7240C/M	25 Mbps		17	25		
	ISO7241A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	13	20		mA
	ISO7241A	1 Mbps		13	20		
	ISO7241C/M	25 Mbps		18	28		
	ISO7242A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	10	16		mA
	ISO7242A	1 Mbps		10	16		
ISO7242C/M	25 Mbps	15		24			
ELECTRICAL CHARACTERISTICS							
I_{OFF}	Sleep mode output current	EN at V_{CC} , Single channel		0			μ A
V_{OH}	High-level output voltage	$I_{OH} = -4$ mA, See Figure 1		$V_{CC} - 0.8$			V
		$I_{OH} = -20$ μ A, See Figure 1		$V_{CC} - 0.1$			
V_{OL}	Low-level output voltage	$I_{OL} = 4$ mA, See Figure 1			0.4		V
		$I_{OL} = 20$ μ A, See Figure 1			0.1		
$V_{I(HYS)}$	Input voltage hysteresis			150			mV
I_{IH}	High-level input current	IN from 0 V to V_{CC}				10	μ A
I_{IL}	Low-level input current			-10			
C_1	Input capacitance to ground	IN at V_{CC} , $V_1 = 0.4 \sin(4E6\pi t)$		2			pF
CMTI	Common-mode transient immunity	$V_1 = V_{CC}$ or 0 V, See Figure 4		25	50		kV/ μ s

SWITCHING CHARACTERISTICS

V_{CC1} and V_{CC2} at 5-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay	See Figure 1	40		95	ns
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				10	
t_{PLH} , t_{PHL}	Propagation delay		18		42	
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				2.5	ns
t_{PLH} , t_{PHL}	Propagation delay		10		23	
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $			1	2	
$t_{sk(o)}$	Channel-to-channel output skew ⁽²⁾	ISO724xA/C			2	ns
		ISO724xM		0	1	
t_r	Output signal rise time	See Figure 1		2		ns
t_f	Output signal fall time			2		
t_{PHZ}	Propagation delay, high-level-to-high-impedance output	See Figure 2		15	20	ns
t_{PZH}	Propagation delay, high-impedance-to-high-level output			15	20	
t_{PLZ}	Propagation delay, low-level-to-high-impedance output			15	20	
t_{PZL}	Propagation delay, high-impedance-to-low-level output			15	20	
t_{fs}	Failsafe output delay time from input power loss	See Figure 3		12		μ s
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter	ISO724xM	150 Mbps NRZ data input, Same polarity input on all channels, See Figure 5		1	ns

(1) Also referred to as pulse skew.

(2) $t_{sk(o)}$ is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

ELECTRICAL CHARACTERISTICS

V_{CC1} at 5-V, V_{CC2} at 3.3-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SUPPLY CURRENT							
I_{CC1}	ISO7240A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	1	3		mA
	ISO7240A	1 Mbps		1	3		
	ISO7240C/M	25 Mbps		7	10.5		
	ISO7241A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	6.5	10		mA
	ISO7241A	1 Mbps		6.5	10		
	ISO7241C/M	25 Mbps		12	18		
	ISO7242A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	10	16		mA
	ISO7242A	1 Mbps		10	16		
ISO7242C/M	25 Mbps	15		24			
I_{CC2}	ISO7240A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	9.5	15		mA
	ISO7240A	1 Mbps		10	15		
	ISO7240C/M	25 Mbps		10.5	17		
	ISO7241A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	8	13		mA
	ISO7241A	1 Mbps		8	13		
	ISO7241C/M	25 Mbps		11.5	18		
	ISO7242A/C/M	Quiescent	$V_1 = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	6	10		mA
	ISO7242A	1 Mbps		6	10		
ISO7242C/M	25 Mbps	9		14			
ELECTRICAL CHARACTERISTICS							
I_{OFF}	Sleep mode output current	EN at VCC, Single channel		0			μ A
V_{OH}	High-level output voltage	$I_{OH} = -4$ mA, See Figure 1	ISO7240	$V_{CC} - 0.4$			V
			ISO724x (5-V side)	$V_{CC} - 0.8$			
				$V_{CC} - 0.1$			
V_{OL}	Low-level output voltage	$I_{OL} = 4$ mA, See Figure 1			0.4		V
			$I_{OL} = 20$ μ A, See Figure 1			0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150		mV	
I_{IH}	High-level input current	IN from 0 V to V_{CC}			10		μ A
I_{IL}	Low-level input current			-10			
C_I	Input capacitance to ground	IN at V_{CC} , $V_I = 0.4 \sin(4E6\pi t)$			2		pF
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See Figure 4		25	50		kV/ μ s

SWITCHING CHARACTERISTICS

V_{CC1} at 5-V, V_{CC2} at 3.3-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t_{PLH} , t_{PHL}	Propagation delay	See Figure 1	40		100	ns	
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				11		
t_{PLH} , t_{PHL}	Propagation delay		20		50		
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				3		
t_{PLH} , t_{PHL}	Propagation delay		ISO724xA	12		29	ns
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				1	2	
$t_{sk(o)}$	Channel-to-channel output skew ⁽²⁾	ISO724xA/C			3	ns	
		ISO724xM			0		1
t_r	Output signal rise time	See Figure 1		2		ns	
t_f	Output signal fall time			2			
t_{PHZ}	Propagation delay, high-level-to-high-impedance output	See Figure 2		15	20	ns	
t_{PZH}	Propagation delay, high-impedance-to-high-level output			15	20		
t_{PLZ}	Propagation delay, low-level-to-high-impedance output			15	20		
t_{PZL}	Propagation delay, high-impedance-to-low-level output			15	20		
t_{fs}	Failsafe output delay time from input power loss	See Figure 3		18		μ s	
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter	ISO724xM	150 Mbps PRBS NRZ data input, Same polarity input on all channels, See Figure 5		1	ns	

(1) Also known as pulse skew

(2) $t_{sk(o)}$ is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

ELECTRICAL CHARACTERISTICS

V_{CC1} at 3.3-V, V_{CC2} at 5-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SUPPLY CURRENT							
I_{CC1}	ISO7240A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	0.5	1		mA
	ISO7240A	1 Mbps		1	2		
	ISO7240C/M	25 Mbps		3	5		
	ISO7241A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	4	7		mA
	ISO7241A	1 Mbps		4	7		
	ISO7241C/M	25 Mbps		6.5	11		
	ISO7242A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	6	10		mA
	ISO7242A	1 Mbps		6	10		
ISO7242C/M	25 Mbps	9		14			
I_{CC2}	ISO7240A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_2 at 3 V	15	22		mA
	ISO7240A	1 Mbps		16	22		
	ISO7240C/M	25 Mbps		17	25		
	ISO7241A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	13	20		mA
	ISO7241A	1 Mbps		13	20		
	ISO7241C/M	25 Mbps		18	28		
	ISO7242A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, All channels, no load, EN_1 at 3 V, EN_2 at 3 V	10	16		mA
	ISO7242A	1 Mbps		10	16		
ISO7242C/M	25 Mbps	15		24			
ELECTRICAL CHARACTERISTICS							
I_{OFF}	Sleep mode output current	EN at VCC, Single channel		0			μ A
V_{OH}	High-level output voltage	$I_{OH} = -4$ mA, See Figure 1	ISO7240	$V_{CC} - 0.4$			V
			ISO724x (5-V side)	$V_{CC} - 0.8$			
		$I_{OH} = -20$ μ A, See Figure 1		$V_{CC} - 0.1$			
V_{OL}	Low-level output voltage	$I_{OL} = 4$ mA, See Figure 1				0.4	V
		$I_{OL} = 20$ μ A, See Figure 1				0.1	
$V_{I(HYS)}$	Input voltage hysteresis			150			mV
I_{IH}	High-level input current	IN from 0 V to V_{CC}				10	μ A
I_{IL}	Low-level input current			-10			
C_I	Input capacitance to ground	IN at V_{CC} , $V_I = 0.4 \sin(4E6\pi t)$		2			pF
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See Figure 4		25	50		kV/ μ s

SWITCHING CHARACTERISTICS

V_{CC1} at 3.3-V and V_{CC2} at 5-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay	See Figure 1	40		100	ns
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				11	
t_{PLH} , t_{PHL}	Propagation delay		22		51	
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $				3	ns
t_{PLH} , t_{PHL}	Propagation delay		12		30	
PWD	Pulse-width distortion ⁽¹⁾ $ t_{PHL} - t_{PLH} $			1	2	
$t_{sk(o)}$	Channel-to-channel output skew ⁽²⁾	ISO724xA/C			2.5	ns
		ISO724xM		0	1	
t_r	Output signal rise time	See Figure 1		2		ns
t_f	Output signal fall time			2		
t_{PHZ}	Propagation delay, high-level-to-high-impedance output	See Figure 2		15	20	ns
t_{PZH}	Propagation delay, high-impedance-to-high-level output			15	20	
t_{PLZ}	Propagation delay, low-level-to-high-impedance output			15	20	
t_{PZL}	Propagation delay, high-impedance-to-low-level output			15	20	
t_{fs}	Failsafe output delay time from input power loss	See Figure 3		12		μ s
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter	ISO724xM	150 Mbps NRZ data input, Same polarity input on all channels, See Figure 5		1	ns

(1) Also known as pulse skew

(2) $t_{sk(o)}$ is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

ELECTRICAL CHARACTERISTICS

V_{CC1} and V_{CC2} at 3.3 V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT	
SUPPLY CURRENT								
I_{CC1}	ISO7240A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, all channels, no load, EN_2 at 3 V	0.5	1		mA	
	ISO7240A	1 Mbps		1	2			
	ISO7240C/M	25 Mbps		3	5			
	I_{CC1}	ISO7241A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, all channels, no load, EN_1 at 3 V, EN_2 at 3 V	4	7		mA
		ISO7241A	1 Mbps		4	7		
		ISO7241C/M	25 Mbps		6.5	11		
		ISO7242A/C/M	Quiescent		6	10		
		ISO7242A	1 Mbps		6	10		
		ISO7242C/M	25 Mbps		9	14		
I_{CC2}	ISO7240A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, all channels, no load, EN_2 at 3 V	9.5	15		mA	
	ISO7240A	1 Mbps		10	15			
	ISO7240C/M	25 Mbps		10.5	17			
	I_{CC2}	ISO7241A/C/M	Quiescent	$V_I = V_{CC}$ or 0 V, all channels, no load, EN_1 at 3 V, EN_2 at 3 V	8	13		mA
		ISO7241A	1 Mbps		8	13		
		ISO7241C/M	25 Mbps		11.5	18		
		ISO7242A/C/M	Quiescent		6	10		
		ISO7242A	1 Mbps		6	10		
		ISO7242C/M	25 Mbps		9	14		
ELECTRICAL CHARACTERISTICS								
I_{OFF}	Sleep mode output current	EN at V_{CC} , single channel		0			μ A	
V_{OH}	High-level output voltage	$I_{OH} = -4$ mA, See Figure 1		$V_{CC} - 0.4$			V	
		$I_{OH} = -20$ μ A, See Figure 1		$V_{CC} - 0.1$				
V_{OL}	Low-level output voltage	$I_{OL} = 4$ mA, See Figure 1		0.4			V	
		$I_{OL} = 20$ μ A, See Figure 1		0.1				
$V_{I(HYS)}$	Input voltage hysteresis			150			mV	
I_{IH}	High-level input current	IN from 0 V or V_{CC}		10			μ A	
I_{IL}	Low-level input current			-10				
C_I	Input capacitance to ground	IN at V_{CC} , $V_I = 0.4 \sin(4E6\pi t)$		2			pF	
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See Figure 4		25	50		kV/ μ s	

SWITCHING CHARACTERISTICS

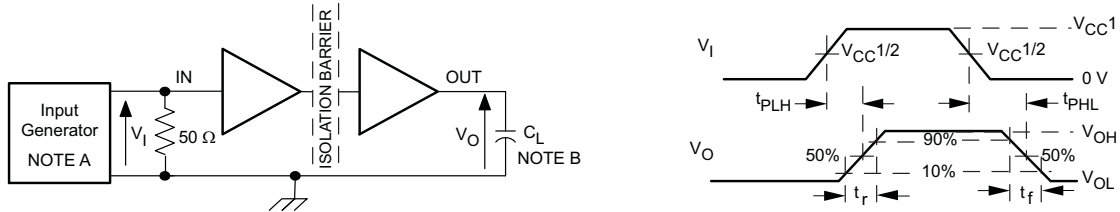
V_{CC1} and V_{CC2} at 3.3-V operation, over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	Propagation delay	ISO724xA	45		110	ns
PWD	Pulse-width distortion $ t_{PHL} - t_{PLH} ^{(1)}$					
t_{PLH} , t_{PHL}	Propagation delay	ISO724xC	25		56	
PWD	Pulse-width distortion $ t_{PHL} - t_{PLH} ^{(1)}$					
t_{PLH} , t_{PHL}	Propagation delay	ISO724xM	12		34	ns
PWD	Pulse-width distortion $ t_{PHL} - t_{PLH} ^{(1)}$					
$t_{sk(o)}$	Channel-to-channel output skew ⁽²⁾	ISO724xA/C			3.5	ns
		ISO724xM		0	1	
t_r	Output signal rise time	See Figure 1		2		
t_f	Output signal fall time			2		
t_{PHZ}	Propagation delay, high-level-to-high-impedance output	See Figure 2		15	20	ns
t_{PZH}	Propagation delay, high-impedance-to-high-level output			15	20	
t_{PLZ}	Propagation delay, low-level-to-high-impedance output			15	20	
t_{PZL}	Propagation delay, high-impedance-to-low-level output			15	20	
t_{fs}	Failsafe output delay time from input power loss	See Figure 3		18		μ s
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter	ISO724xM		1		ns

(1) Also referred to as pulse skew.

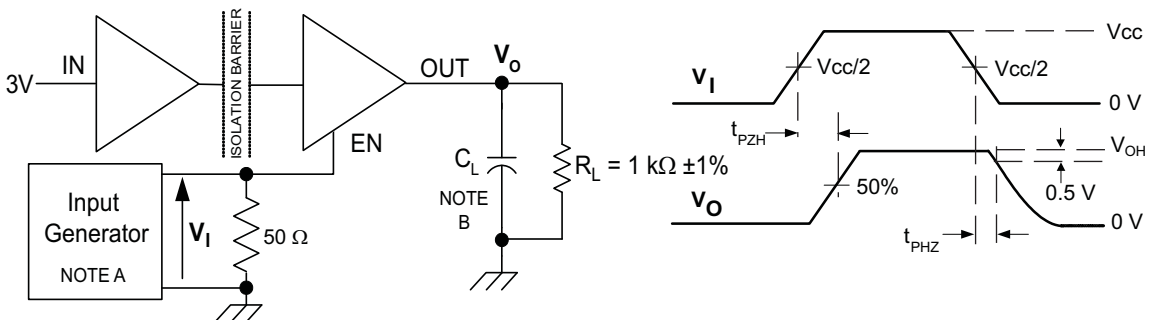
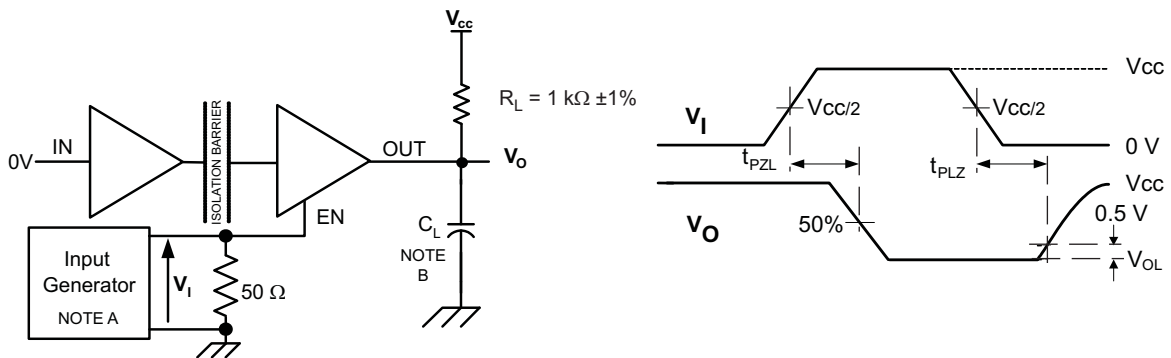
(2) $t_{sk(o)}$ is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

PARAMETER MEASUREMENT INFORMATION



- A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 50 kHz, 50% duty cycle, $t_r \leq$ 3 ns, $t_f \leq$ 3 ns, $Z_0 = 50\Omega$.
- B. $C_L = 15$ pF and includes instrumentation and fixture capacitance within $\pm 20\%$.

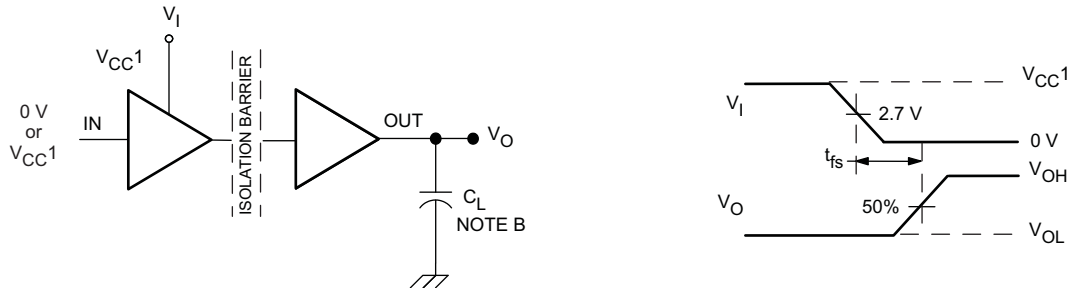
Figure 1. Switching Characteristic Test Circuit and Voltage Waveforms



- A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 50 kHz, 50% duty cycle, $t_r \leq$ 3 ns, $t_f \leq$ 3 ns, $Z_0 = 50\Omega$.
- B. $C_L = 15$ pF and includes instrumentation and fixture capacitance within $\pm 20\%$.

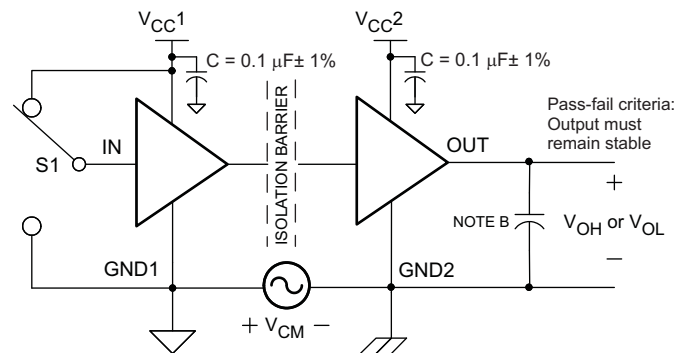
Figure 2. Enable/Disable Propagation Delay Time Test Circuit and Waveform

PARAMETER MEASUREMENT INFORMATION (continued)



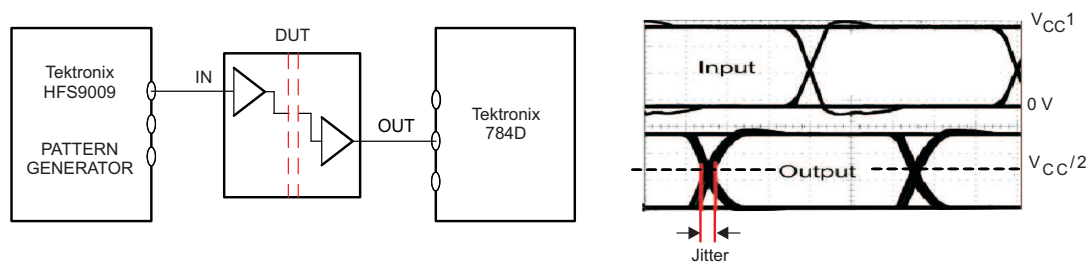
- A. $C_L = 15 \text{ pF}$ and includes instrumentation and fixture capacitance within $\pm 20\%$.
- B. The input pulse is supplied by a generator having the following characteristics: $\text{PRR} \leq 50 \text{ kHz}$, 50% duty cycle, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$, $Z_O = 50 \Omega$.

Figure 3. Failsafe Delay Time Test Circuit and Voltage Waveforms



- A. $C_L = 15 \text{ pF}$ and includes instrumentation and fixture capacitance within $\pm 20\%$.
- B. The input pulse is supplied by a generator having the following characteristics: $\text{PRR} \leq 50 \text{ kHz}$, 50% duty cycle, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$, $Z_O = 50 \Omega$.

Figure 4. Common-Mode Transient Immunity Test Circuit and Voltage Waveform



NOTE: PRBS bit pattern run length is $2^{16} - 1$. Transition time is 800 ps. NRZ data input has no more than five consecutive 1s or 0s.

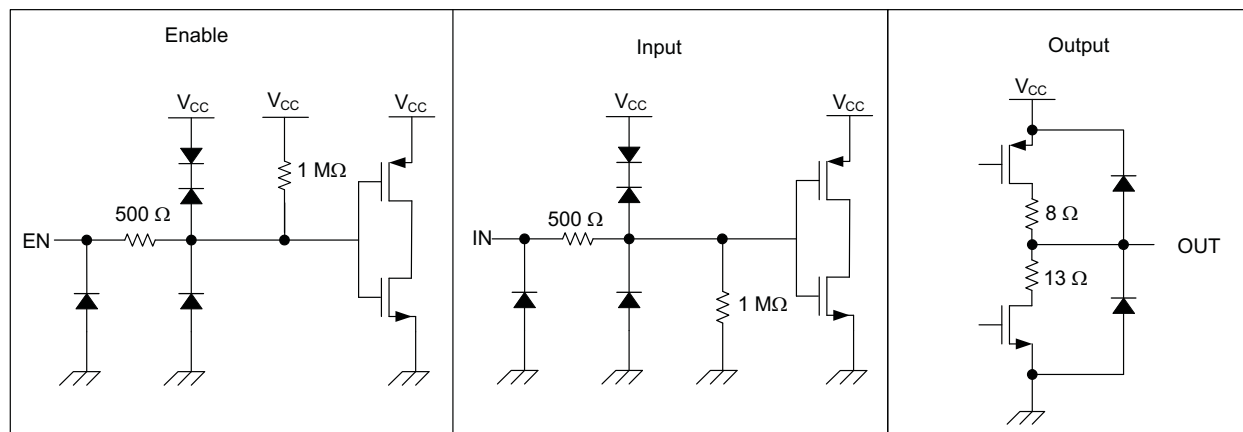
Figure 5. Peak-to-Peak Eye-Pattern Jitter Test Circuit and Voltage Waveform

DEVICE INFORMATION

PACKAGE CHARACTERISTICS

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
L(I01) Minimum air gap (Clearance)	Shortest terminal-to-terminal distance through air	7.7			mm
L(I02) Minimum external tracking (Creepage)	Shortest terminal-to-terminal distance across the package surface	8.1			mm
Minimum Internal Gap (Internal Clearance)	Distance through the insulation	0.008			mm
R _{IO} Isolation resistance	Input to output, V _{IO} = 500 V, all pins on each side of the barrier tied together creating a two-terminal device	>10 ¹²			Ω
C _{IO} Barrier capacitance Input to output	V _I = 0.4 sin (4E6πt)		2		pF
C _I Input capacitance to ground	V _I = 0.4 sin (4E6πt)		2		pF

DEVICE I/O SCHEMATICS



REGULATORY INFORMATION

VDE	CSA	UL
Certified according to IEC 60747-5-2	Approved under CSA Component Acceptance Notice	Recognized under 1577 Component Recognition Program ⁽¹⁾
File Number: Pending	File Number: Pending	File Number: E181974

(1) Production tested ≥ 3000 Vrms for 1 second in accordance with UL 1577.

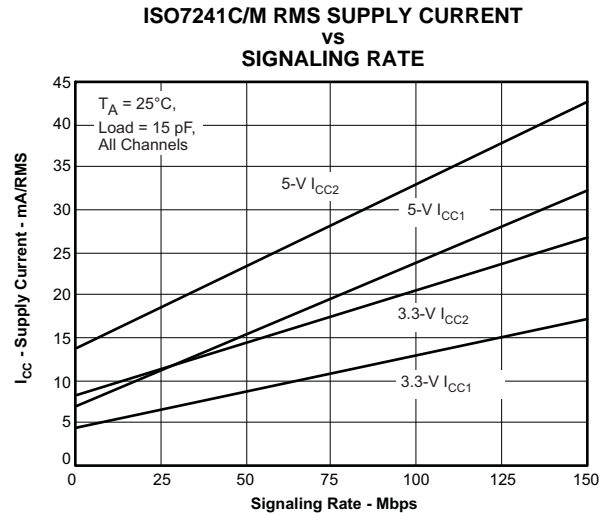
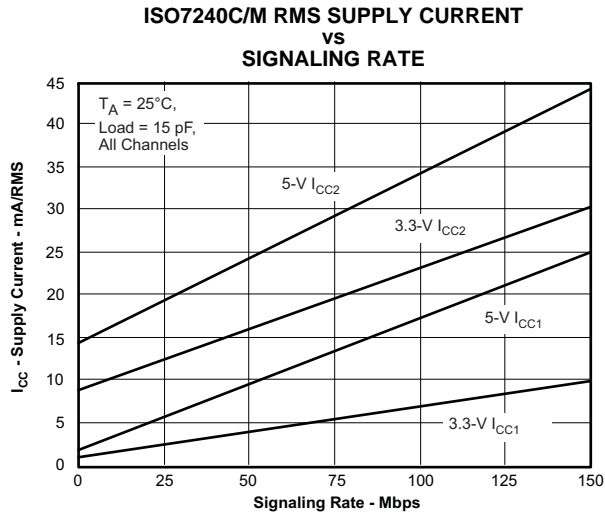
THERMAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

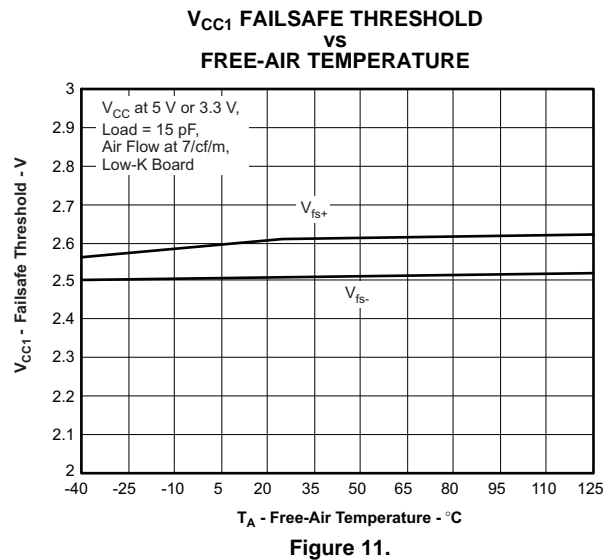
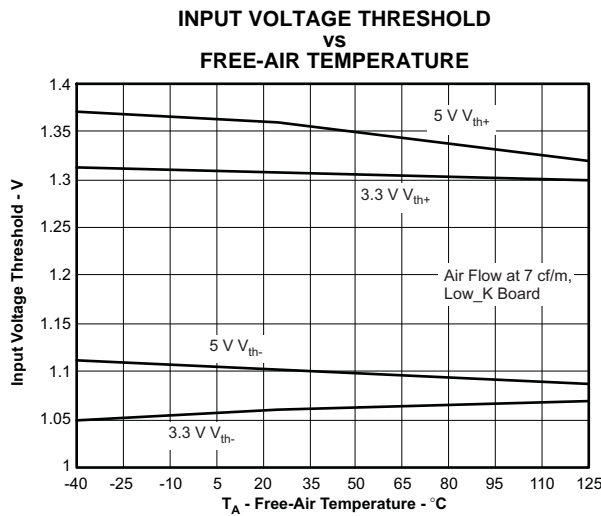
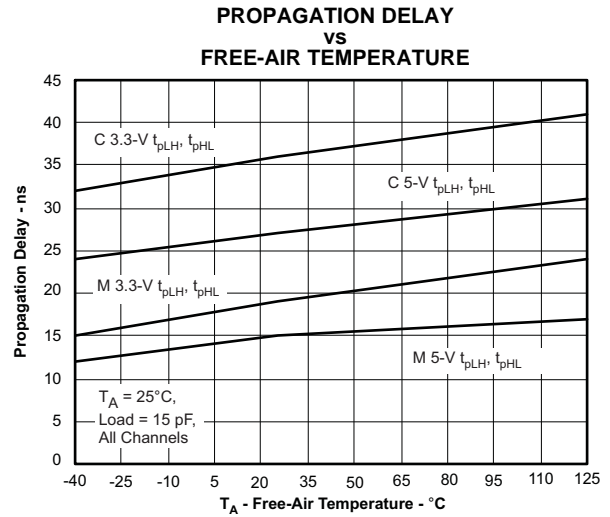
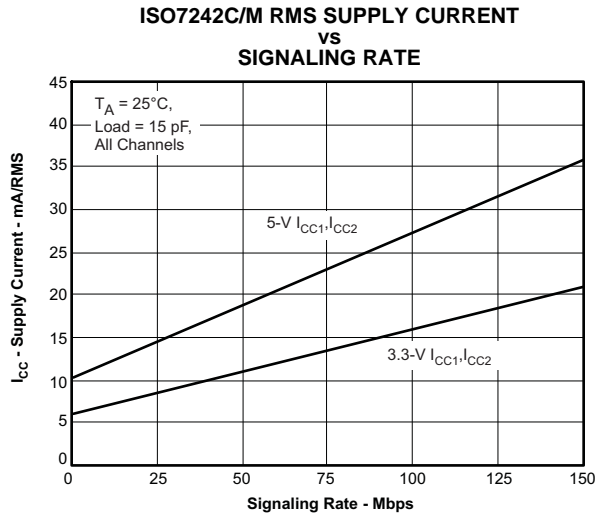
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
θ_{JA} Junction-to-air	Low-K Thermal Resistance ⁽¹⁾		168		°C/W
	High-K Thermal Resistance		96.1		
θ_{JB} Junction-to-Board Thermal Resistance			61		°C/W
θ_{JC} Junction-to-Case Thermal Resistance			48		°C/W
P_D Device Power Dissipation	$V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150^\circ$ C, $C_L = 15$ pF, Input a 50% duty cycle square wave			220	mW

(1) Tested in accordance with the Low-K or High-K thermal metric definitions of EIA/JESD51-3 for leaded surface mount packages.

TYPICAL CHARACTERISTIC CURVES



TYPICAL CHARACTERISTIC CURVES (continued)



TYPICAL CHARACTERISTIC CURVES (continued)

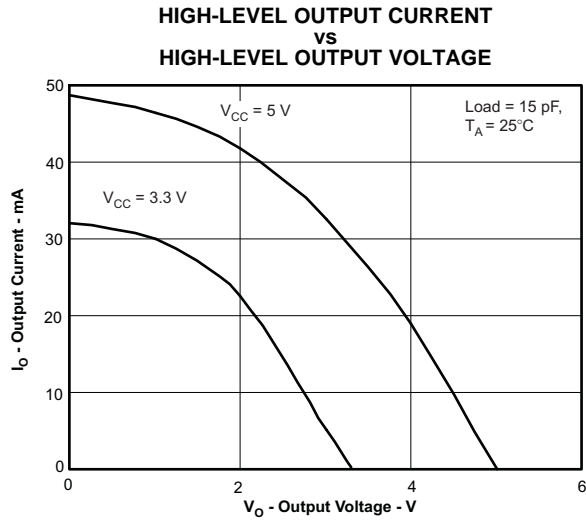


Figure 12.

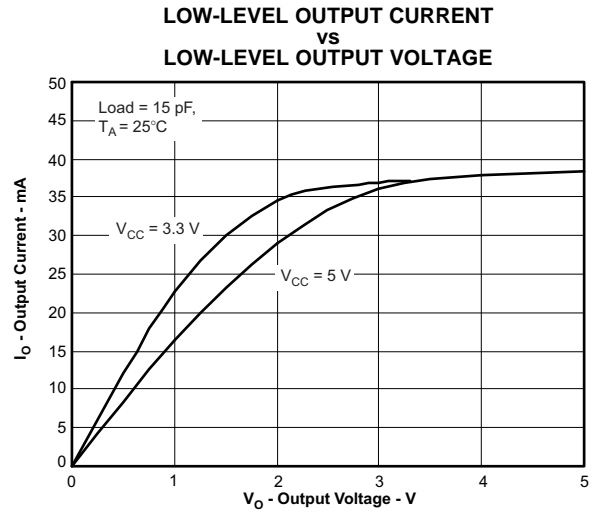


Figure 13.

APPLICATION INFORMATION

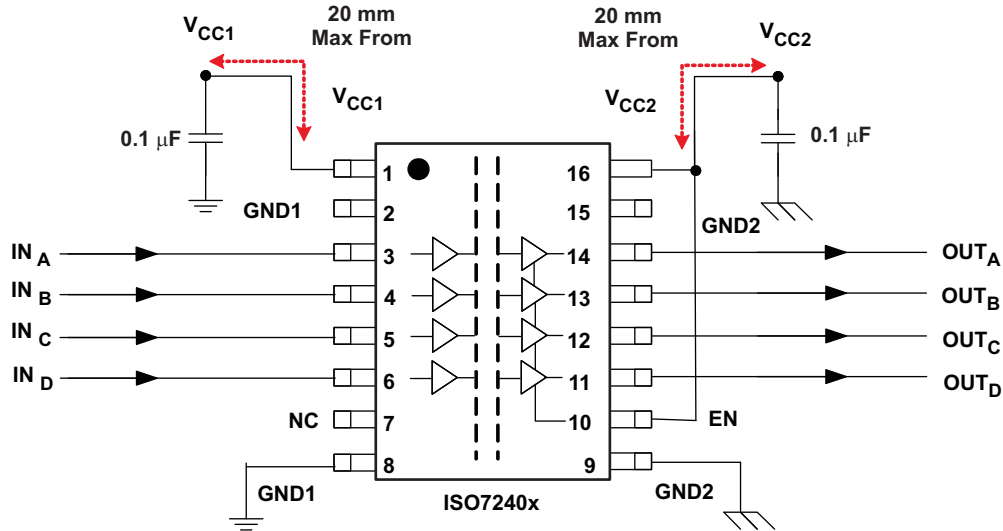


Figure 14. Typical ISO724x Application Circuit

LIFE EXPECTANCY vs. WORKING VOLTAGE

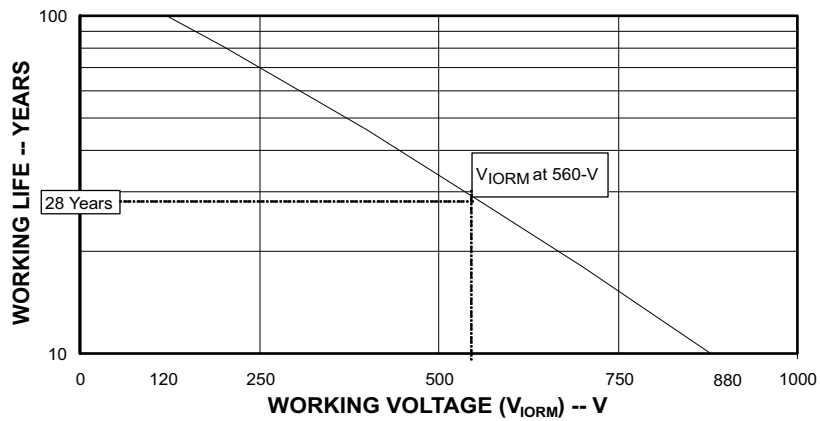


Figure 15. Time-Dependant Dielectric Breakdown Testing Results

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ISO7240ADW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240ADWG4	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240ADWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240ADWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240CDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240CDWG4	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240CDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240CDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240MDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240MDWG4	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240MDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7240MDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241ADW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241ADWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241CDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241CDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241MDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7241MDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242ADW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242ADWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242CDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242CDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242MDW	ACTIVE	SOIC	DW	16	49	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
ISO7242MDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

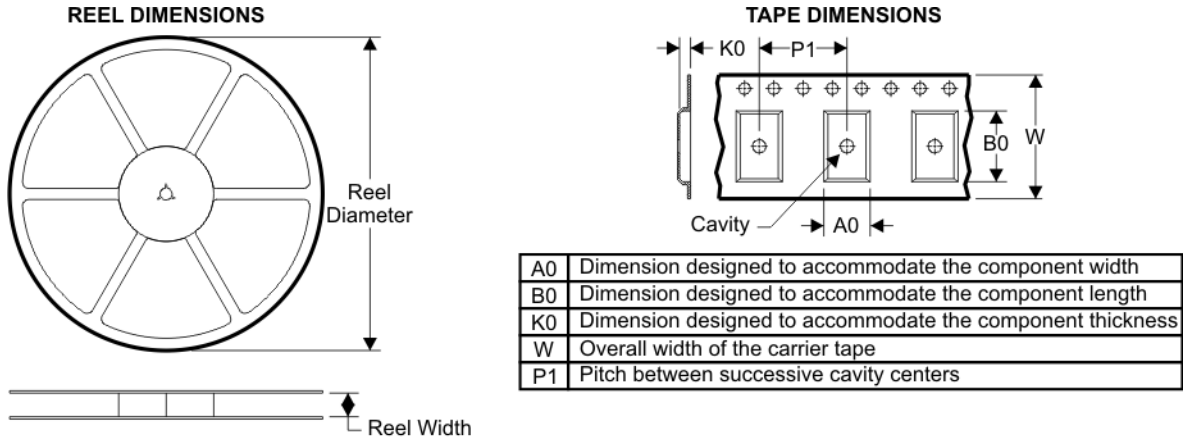
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

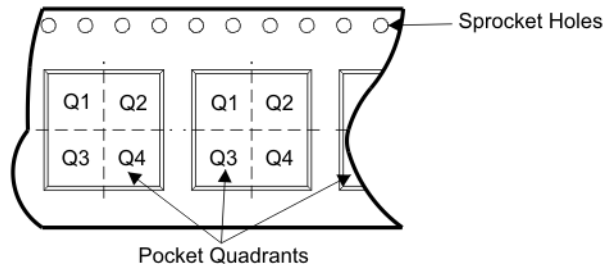
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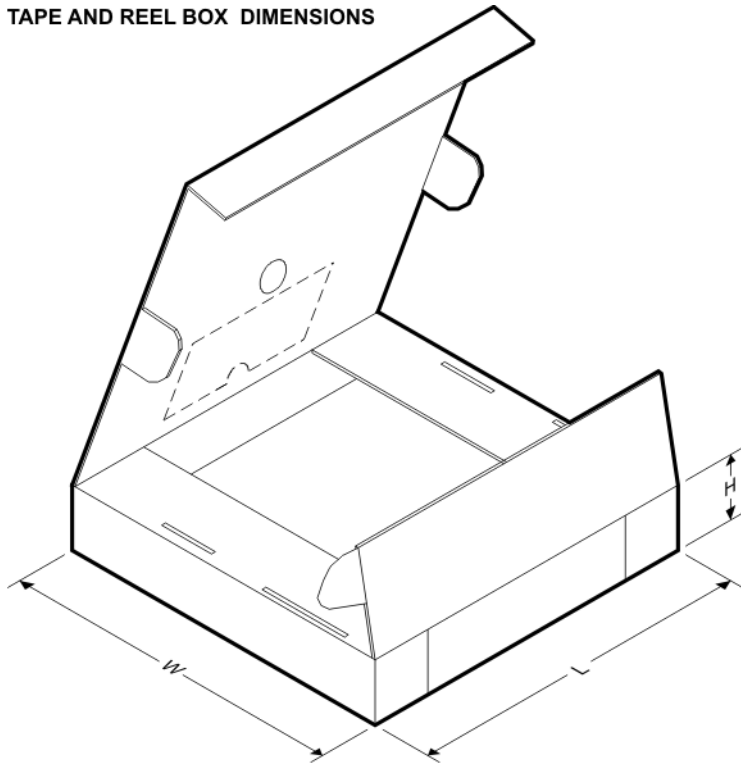


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO7240ADWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7240CDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7240MDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7241ADWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7241CDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7241MDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7242ADWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7242CDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1
ISO7242MDWR	DW	16	SITE 35	330	16	10.9	10.78	3.0	12	16	Q1

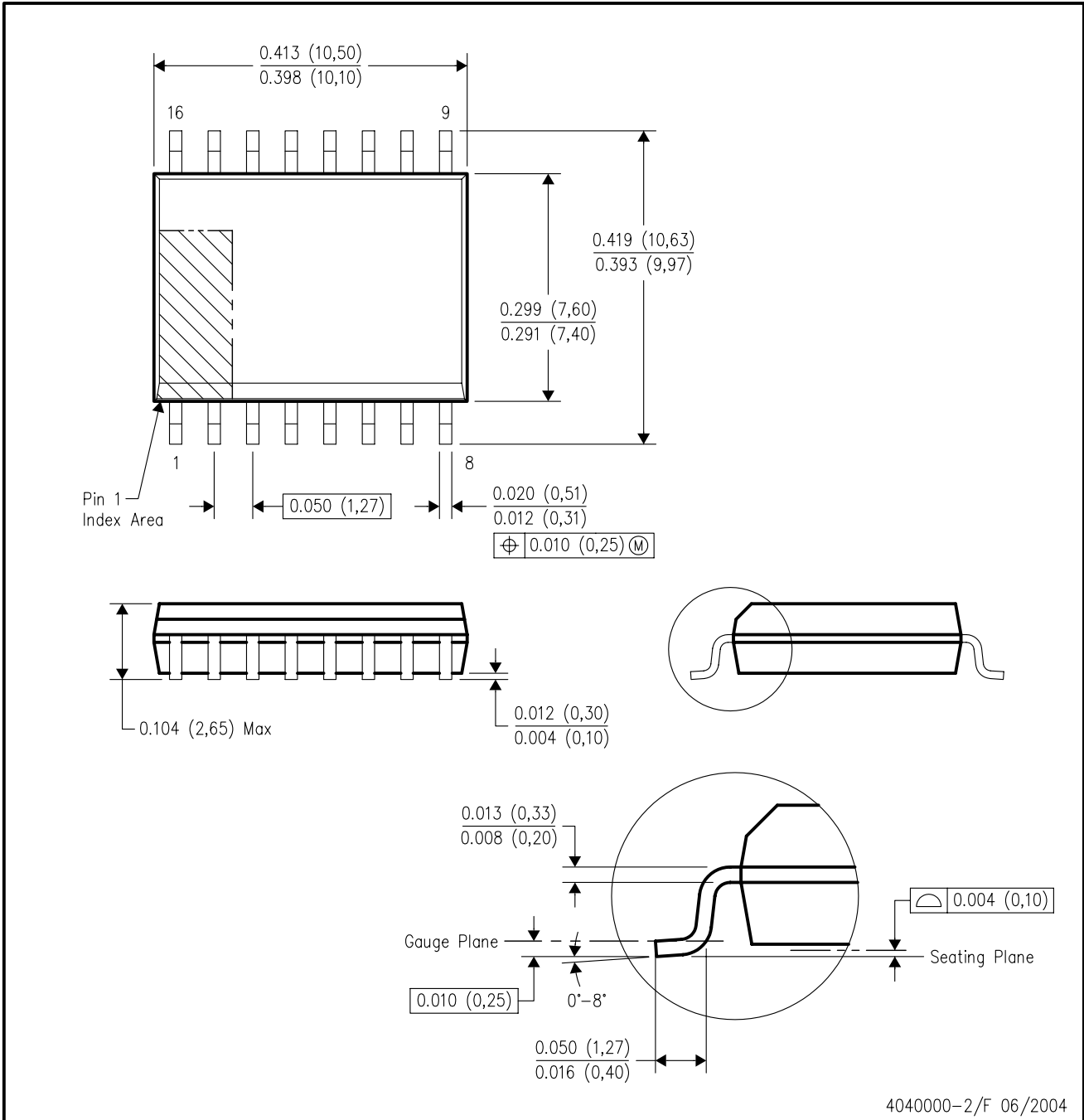
TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
ISO7240ADWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7240CDWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7240MDWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7241ADWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7241CDWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7241MDWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7242ADWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7242CDWR	DW	16	SITE 35	406.0	348.0	63.0
ISO7242MDWR	DW	16	SITE 35	406.0	348.0	63.0

DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-2/F 06/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AA.

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